

## HIGH-SPEED 2.5V 16/8K X 9 SYNCHRONOUS PIPELINED DUAL-PORT STATIC RAM

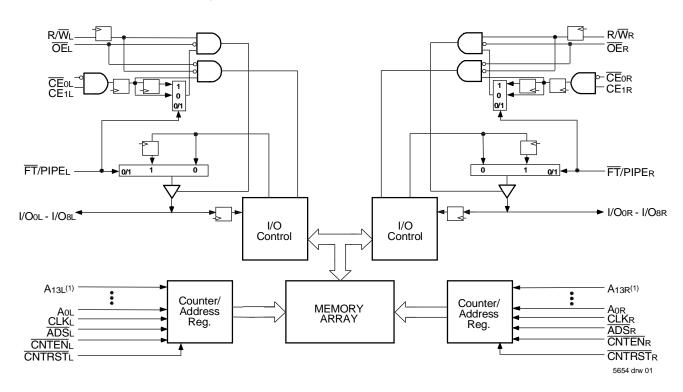
### PRELIMINARY IDT70T9169/59L

### **Features**

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
  - Commercial: 7.5/9/12ns (max.)
  - Industrial: 9ns (max.)
- Low-power operation
  - IDT70T9169/59LActive: 225mW (typ.)Standby: 1.5mW (typ.)
- Flow-Through or Pipelined output mode on either Port via the FT/PIPE pins
- Counter enable and reset features
- Dual chip enables allow for depth expansion without additional logic

- Full synchronous operation on both ports
  - 4.0ns setup to clock and 0.5ns hold on all control, data, and address inputs
  - Data input, address, and control registers
  - Fast 7.5ns clock to data out in the Pipelined output mode
  - Self-timed write allows fast cycle time
  - 12ns cycle time, 83MHz operation in Pipelined output mode
- ◆ LVTTL- compatible, single 2.5V (±100mV) power supply
- Industrial temperature range (-40°C to +85°C) is available for 66MHz
- Available in a 100-pin Thin Quad Flatpack (TQFP) and 100pin fine pitch Ball Grid Array (fpBGA) packages.

## **Functional Block Diagram**



### NOTE:

1. A<sub>13</sub> is a NC for IDT70T9159.

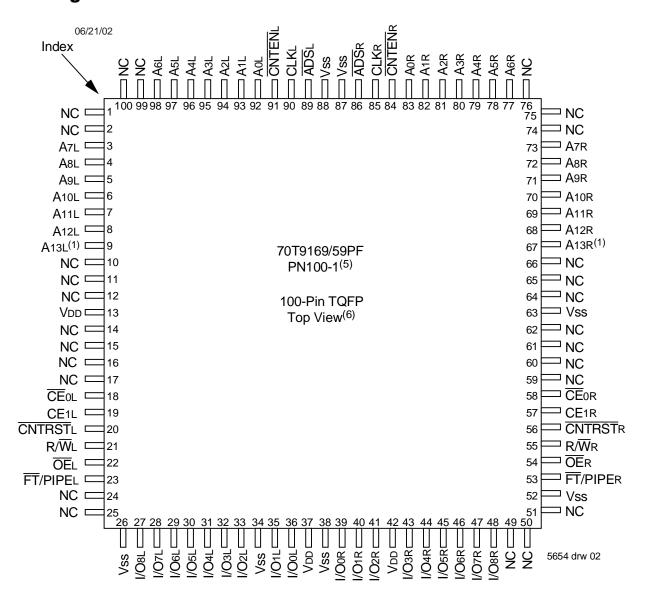
**JULY 2002** 

## **Description**

The IDT70T9169/59 is a high-speed 16/8K x 9 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times.

With an input data register, the IDT70T9169/59 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by  $\overline{\text{CE}}$ 0 and CE1, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 225mW of power.

## Pin Configurations (1,2,3,4)



- 1. A<sub>13</sub> is a NC for IDT70T9159.
- 2. All VDD pins must be connected to power supply.
- 3. All Vss pins must be connected to ground supply.
- 4. Package body is approximately 14mm x 14mm x 1.4mm.
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

# Pin Configurations (con't.) $^{(1,2,3,4)}$

70T9169/59BF BF100<sup>(5)</sup>

100-Pin fpBGA Top View<sup>(6)</sup>

06/21/02

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10
A6R	<b>A</b> 9R	A12R	NC	Vss	Vss	NC	<b>R/W</b> R	Vss	NC
B1	B2	B3	B4	B5	B6	B7	B8	B9	B10
A4R	<b>A</b> 5R	<b>A</b> 8R	<b>A</b> 10R	NC	NC	NC	OEr	NC	<b>I/O</b> 6R
C1 A3R	C2 NC	C3 NC	C4 <b>A</b> 7R	C5 NC	CE <sub>0R</sub>		C8 PL/FTR	C9 I/ <b>O</b> 7R	C10 I/ <b>O</b> 3R
D1	D2	D3	D4	D5		D7	D8	D9	D10
Aor	CLKR	<b>A</b> 1R	<b>A</b> 2R	<b>A</b> 11R		CNTRST <sub>R</sub>	<b>I/O</b> 8R	I/O5R	<b>I/O</b> 1R
E1	E2	E3	E4	E5	E6	E7	E8	E9	E10
Vss	ADS <sub>R</sub>	CNTEN <sub>R</sub>	A1L	ADSL	Vss	I/ <b>O</b> 4R	I/ <b>O</b> 2R	I/O0R	VDD
F1	F2	F3	F4	F5	F6	F7	F8	F9	F10
Vss	CLKL	Aol	A3L	Vdd	Vss	Vdd	I/ <b>O</b> 2L	I/O1L	I/ <b>O</b> 0L
G1	G2	G3	G4	G5	G6	<sub>G7</sub>	G8	<sub>G9</sub>	G10
CNTEN∟	NC	A5L	A12L	NC	R/WL	NC	I/O4L	Vss	I/ <b>O</b> 3L
H1	H2	H3	H4	H5	H6	H7	H8	H9	H10
A2L	A4L	<b>A</b> 9L	A13L <sup>(1)</sup>	NC	CE1L	NC	I/O7L	I/O6L	I/O5L
J1	J2	J3	J4	J5	J6	J7	<sup>J8</sup>	<sup>J9</sup>	J10
NC	A7L	A10L	NC	NC	NC	OEL	Vss	Vss	<b>I/O</b> 8L
K1	K2	K3	K4	K5	K6	'``'	K8	k9	K10
A6L	A8L	A11L	NC	Vdd	Vdd		CNTRST∟	PL/FTL	NC

5654 drw 03

- 1. A<sub>13</sub> is a NC for IDT70T9159.
- 2. All  $V_{\mbox{\scriptsize DD}}$  pins must be connected to power supply.
- 3. All Vss pins must be connected to ground supply.
- 4. Package body is approximately 10mm x 10mm x 1.4mm with 0.8mm ball pitch.
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

### **Pin Names**

Left Port	Right Port	Names		
CEOL, CE1L	CEOR, CE1R	Chip Enables		
R/WL	R/W̄R	Read/Write Enable		
ŌĒL	<del>OE</del> R	Output Enable		
A0L - A13L <sup>(1)</sup>	A0R - A13R <sup>(1)</sup>	Address		
I/OoL - I/O8L	1/Oor - 1/O8R	Data Input/Output		
CLKL	CLKR	Clock		
ADS <sub>L</sub>	ĀDS <sub>R</sub>	Address Strobe		
CNTENL	<u>CNTEN</u> R	Counter Enable		
CNTRST <sub>L</sub>	<u>CNTRST</u> R	Counter Reset		
FT/PIPEL	FT/PIPER	Flow-Through/Pipeline		
V	DD	Power (2.5V)		
V	SS	Ground (0V)		

5654 tbl 01

### NOTE:

1. A<sub>13</sub> is a NC for IDT70T9159.

# **Truth Table** I—Read/Write and Enable Control<sup>(1,2,3)</sup>

ŌĒ	CLK	Œ₀	CE <sub>1</sub>	R/W	I/O <sub>0-8</sub>	Mode
Х	1	Н	Х	Χ	High-Z	Deselected—Power Down
Х	1	Х	L	Х	High-Z	Deselected—Power Down
Х	1	L	Н	L	DATAIN	Write
L	$\uparrow$	L	Н	Н	DATA <sub>OUT</sub>	Read
Н	Χ	L	Н	Χ	High-Z	Outputs Disabled

5654 tbl 02

- 1. "H" = V<sub>IH</sub>, "L" = V<sub>IL</sub>, "X" = Don't Care. 2. ADS, CNTEN, CNTRST = X.
- 3.  $\overline{\text{OE}}$  is an asynchronous input signal.

## **Truth Table II—Address Counter Control**(1,2)

External Address	Previous Internal Address	Internal Address Used	CLK	ĀDS	CNTEN	CNTRST	I/O <sup>(3)</sup>	MODE
An	Х	An	<b>↑</b>	L <sup>(4)</sup>	Х	Н	Dvo (n)	External Address Used
Х	An	An + 1	<b>↑</b>	Н	L <sup>(5)</sup>	Н	Dvo(n+1)	Counter Enabled—Internal Address generation
Х	An + 1	An + 1	1	Н	Н	Н	Dvo(n+1)	External Address Blocked—Counter disabled (An + 1 reused)
Х	Х	A0	1	Χ	Х	L <sup>(4)</sup>	Dvo(0)	Counter Reset to Address 0

5654 tbl 03 NOTES:

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care.
- 2.  $\overline{CE}_0$  and  $\overline{OE} = V_{IL}$ ; CE1 and  $R/\overline{W} = V_{IH}$ .
- 3. Outputs configured in Flow-Through Output mode: if outputs are in Pipelined mode the data out will be delayed by one cycle.
- 4. ADS and CNTRST are independent of all other signals including CEo and CE1.
- 5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CEo and CE1.

**Recommended Operating Temperature and Supply Voltage** 

Grade	Ambient Temperature <sup>(1)</sup>	GND	<b>V</b> DD
Commercial	0°C to +70°C	OV	2.5V <u>+</u> 100mV
Industrial	-40°C to +85°C	0V	2.5V <u>+</u> 100mV

1. This is the parameter Ta. This is the "instant on" case temperature.

## **Recommended DC Operating Conditions**

Symbol	Parameter	Min.	Тур.	Max.	Unit
V dd	Supply Voltage	2.4	2.5	2.6	V
Vss	Ground	0	0	0	V
VIH	Input High Voltage	1.7	_	V DD+ 0.3 V (2)	V
VIL	Input Low Voltage	-0.3 <sup>(1)</sup>	_	0.7	V

5654 tbl 05

2. VTERM must not exceed VDD +0.3V.

1.  $VIL \ge -1.5V$  for pulse width less than 10 ns.

## Absolute Maximum Ratings(1)

Symbol	Rating	Commercial & Industrial	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +3.6	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-65 to +150	°C
Іоит	DC Output Current	50	mA

NOTES:

NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed VDD + 0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to  $\leq$  20mA for the period of VTERM  $\geq$  VDD + 0.3V.

## Capacitance<sup>(1)</sup>

### $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter	Conditions <sup>(2)</sup>	Max.	Unit
CIN	Input Capacitance	$V_{IN} = 3dV$	9	pF
Соит <sup>(3)</sup>	Output Capacitance	Vout = 3dV	10	pF

5654 tbl 07

- 1. These parameters are determined by device characterization, but are not
- 2. 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
- 3. Cout also references Ci/o.

5654 tb108

5654 tbl 09

## **DC Electrical Characteristics Over the Operating** Temperature Supply Voltage Range (VDD = 2.5V ± 100mV)

			70T91		
Symbol	Parameter	Test Conditions		Max.	Unit
ILI	Input Leakage Current <sup>(1)</sup>	$V_{DD} = 2.6V$ , $V_{IN} = 0V$ to $V_{DD}$	_	5	μA
ILO	Output Leakage Current	$\overline{\text{CE}}$ = VIH or CE1 = VIL, VOUT = 0V to VDD	_	5	μA
Vol	Output Low Voltage	IoL = +2mA	_	0.4	٧
Vон	Output High Voltage	IoH = -2mA	2.0	_	V

1. At  $Vcc \le 2.0V$  input leakages are undefined.

## **DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range**(3) (VDD = 2.5V ± 100mV)

					70T9169/59L7 Com'l Only		70T9169/59L9 Com'l & Ind		70T9169/59L12 Com'l Only		
Symbol	Parameter	Test Condition	Versio	Version		Max.	Typ. <sup>(4)</sup>	Max.	Typ. <sup>(4)</sup>	Max.	Unit
IDD	Dynamic Operating	CEL and CER= VIL,	COM'L	L	80	200	75	175	70	150	mA
	Current (Both Ports Active)	Outputs Disabled, f = f <sub>MAX</sub> <sup>(1)</sup>	IND	L		_	75	220			
ISB1	Standby Current	CEL = CER = VIH	COM'L	L	20	60	20	50	20	40	mA
	(Both Ports - TTL Level Inputs)	$f = f_{MAX}^{(1)}$	IND	L		_	20	70			
ISB2	Standby	CE"A" = VL and	COM'L	L	50	115	47	100	45	85	mA
	Current (One Port - TTL Level Inputs)	CE"B" = VH <sup>(5)</sup> Active Port Outputs Disabled, f=fMAX <sup>(1)</sup>	IND	L	_	_	47	190	_	_	
ISB3	Full Standby	Both Ports CEL and	COM'L	L	0.1	3.0	0.1	3.0	0.1	3.0	mA
	Current (Both Ports - CMOS Level Inputs)	$\overline{\text{CER}} \ge \text{VDD} - 0.2\text{V},$ $\text{VIN} \ge \text{VDD} - 0.2\text{V} \text{ or}$ $\text{VIN} \le 0.2\text{V}, f = 0^{(2)}$	IND	L	_	_	0.1	3.0	_	_	
ISB4	0 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -		COM'L	L	50	115	47	100	45	85	mA
	Current (One Port - CMOS Level Inputs)		IND	L	-	-	47	190	_	_	

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 2.5V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. VDD = 2.5V, TA = 25°C for Typ, and are not production tested. IDD DC(f=0) = 75mA (Typ).
- 5.  $\overline{CE}x = VIL \text{ means } \overline{CE}_0x = VIL \text{ and } CE_1x = VIH$ 
  - $\overline{CE}x = VIH \text{ means } \overline{CE}OX = VIH \text{ or } CE1X = VIL$
  - $\overline{\text{CE}}\text{x} \leq 0.2 \text{V}$  means  $\overline{\text{CE}}\text{ox} \leq 0.2 \text{V}$  and  $\text{CE1x} \geq \text{V}\text{DD}$  0.2 V
  - $\overline{\text{CE}}\text{x} \ge \text{V}_{\text{DD}}$  0.2V means  $\overline{\text{CE}}_{\text{0}}\text{x} \ge \text{V}_{\text{DD}}$  0.2V or  $\text{CE}_{1}\text{x} \le 0.2\text{V}$
  - "X" represents "L" for left port or "R" for right port.

### **AC Test Conditions**

Input Pulse Levels	GND to 2.5V
Input Rise/Fall Times	2ns Max.
Input Timing Reference Levels	1.25V
Output Reference Levels	1.25V
Output Load	Figures 1 and 2

5654 tbl 10

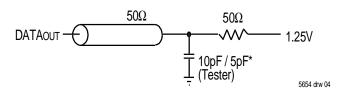


Figure 1. AC Output Test load. \*(For tcklz, tckHz, tolz, and toHz).

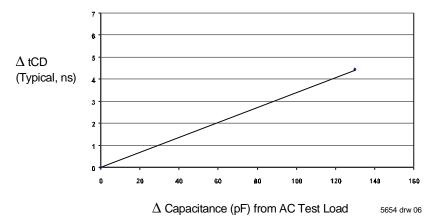


Figure 2. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing) $^{(3)}$  (VDD = 2.5V ± 100mV, TA = 0°C to +70°C)

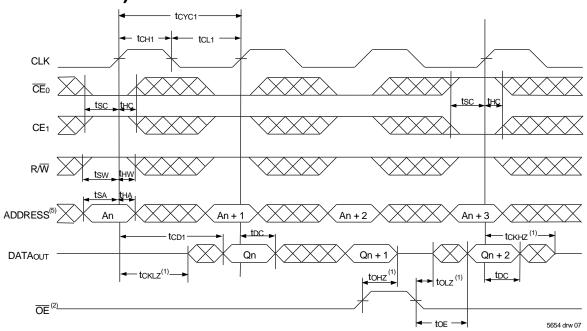
		70T91	69/59L7 I Only	70T91	59/59L9 & Ind	70T9169/59L12 Com'l Only		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) <sup>(2)</sup>	22	_	25	_	30	_	ns
tcyc2	Clock Cycle Time (Pipelined) <sup>(2)</sup>	12	_	15	_	20	_	ns
tcH1	Clock High Time (Flow-Through) <sup>(2)</sup>	7.5	_	12	_	12	_	ns
tcl1	Clock Low Time (Flow-Through) <sup>(2)</sup>	7.5	_	12	_	12	_	ns
tcH2	Clock High Time (Pipelined) <sup>(2)</sup>	5	_	6	_	8	_	ns
tCL2	Clock Low Time (Pipelined) <sup>(2)</sup>	5	_	6		8	_	ns
tr	Clock Rise Time	_	3	_	3	_	3	ns
tr	Clock Fall Time	_	3	_	3	_	3	ns
tsa	Address Setup Time	4	_	4	_	4	_	ns
tha	Address Hold Time	0	_	1	_	1	_	ns
tsc	Chip Enable Setup Time	4	_	4	_	4	_	ns
tнc	Chip Enable Hold Time	0	_	1	_	1	_	ns
tsB	Byte Enable Setup Time	4	_	4	_	4	_	ns
tнв	Byte Enable Hold Time	0	_	1	_	1	_	ns
tsw	R/W Setup Time	4	_	4	_	4	_	ns
thw	R/W Hold Time	0	_	1	_	1	_	ns
tsp	Input Data Setup Time	4	_	4	_	4	_	ns
thd	Input Data Hold Time	0	_	1	_	1	_	ns
tsad	ADS Setup Time	4	_	4	_	4	_	ns
thad	ADS Hold Time	0	_	1	_	1	_	ns
tscn	CNTEN Setup Time	4	_	4	_	4	_	ns
then	CNTEN Hold Time	0	_	1	_	1	_	ns
tsrst	CNTRST Setup Time	4	_	4	_	4	_	ns
thrst	CNTRST Hold Time	0	_	1		1	_	ns
toe	Output Enable to Data Valid	_	7.5	_	9	_	12	ns
tolz	Output Enable to Output Low-Z <sup>(1)</sup>	2	_	2	_	2	_	ns
tонz	Output Enable to Output High-Z <sup>(1)</sup>	1	7	1	7	1	7	ns
tcD1	Clock to Data Valid (Flow-Through)(2)	_	18	_	20	_	25	ns
tcD2	Clock to Data Valid (Pipelined) <sup>(2)</sup>	_	7.5	_	9	_	12	ns
toc	Data Output Hold After Clock High	2	_	2	_	2	_	ns
tckHz	Clock High to Output High-Z <sup>(1)</sup>	2	9	2	9	2	9	ns
tcklz	Clock High to Output Low-Z <sup>(1)</sup>	2	_	2		2	_	ns
Port-to-Port I	Delay							
tcwdd	Write Port Clock High to Read Data Delay	_	28		35	_	40	ns
tccs	Clock-to-Clock Setup Time	_	10	_	15	_	15	ns

<sup>1.</sup> Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

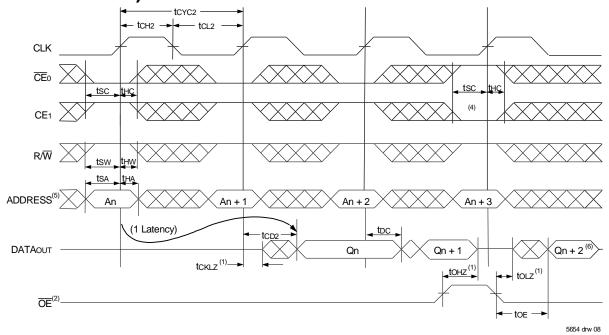
<sup>2.</sup> The Pipelined output parameters (tcyc2, tcp2) to either the Left or Right ports when FT/PIPE = VIH. Flow-Through parameters (tcyc1, tcp1) apply when FT/PIPE = VIL for

<sup>3.</sup> All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE), FT/PIPER and FT/PIPEL

# Timing Waveform of Read Cycle for Flow-Through Output $(\overline{FT}/PIPE"x" = VIL)^{(3,6)}$

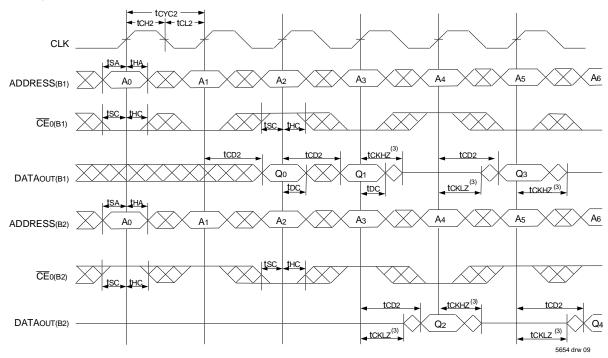


# Timing Waveform of Read Cycle for Pipelined Operation $(\overline{FT}/PIPE"x" = VIH)^{(3,6)}$

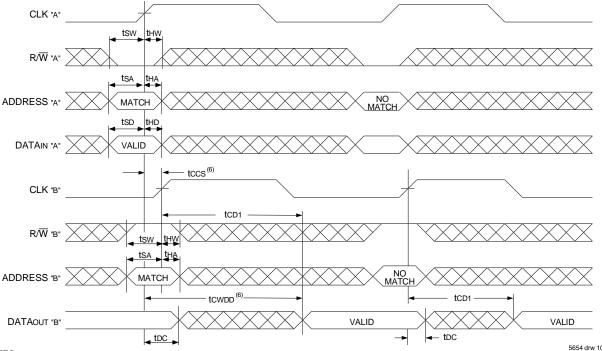


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2.  $\overline{\text{OE}}$  is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. ADS = VIL, CNTEN and CNTRST = VIH.
- The output is disabled (High-Impedance state) by Œo = VIH or CE1 = VIL following the next rising edge of the clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 6. "X" here denotes Left or Right port. The diagram is with respect to that port.

## Timing Waveform of a Bank Select Pipelined Read (1,2)

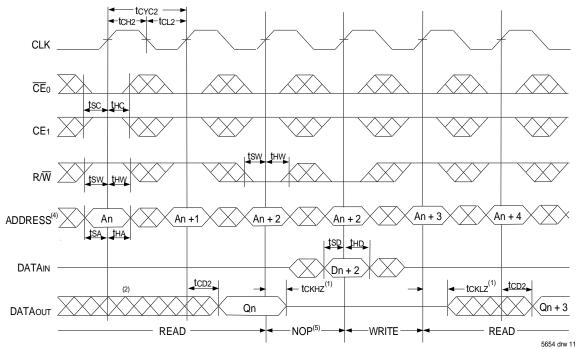


## Timing Waveform of Write with Port-to-Port Flow-Through Read<sup>(4,5,7)</sup>

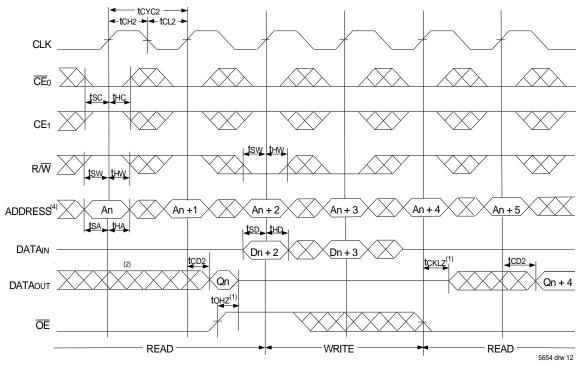


- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70T9169/59 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2.  $\overline{OE}$  and  $\overline{ADS}$  = VIL; CE1(B1), CE1(B2), RW,  $\overline{CNTEN}$ , and  $\overline{CNTRST}$  = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. CEo and ADS = VIL; CE1, CNTEN, and CNTRST = VIH.
- 5.  $\overline{OE}$  = V<sub>IL</sub> for the Right Port, which is being read from.  $\overline{OE}$  = V<sub>IH</sub> for the Left Port, which is being written to.
- If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwbb.
  If tccs > maximum specified, then data from right port READ is not valid until tccs + tcb1. tcwbb does not apply in this case.
- 7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite from Port "A".

# Timing Waveform of Pipelined Read-to-Write-to-Read ( $\overline{OE} = V_{IL}$ )<sup>(3)</sup>

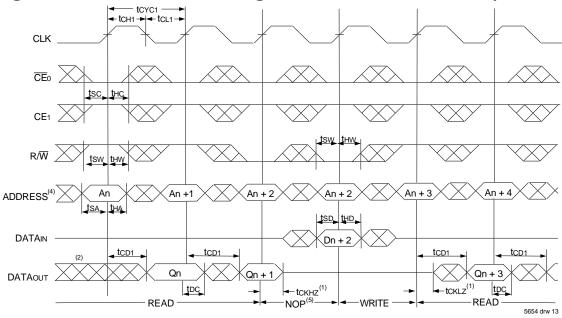


## Timing Waveforn of Pipelined Read-to-Write-to-Read (OE Controlled)(3)

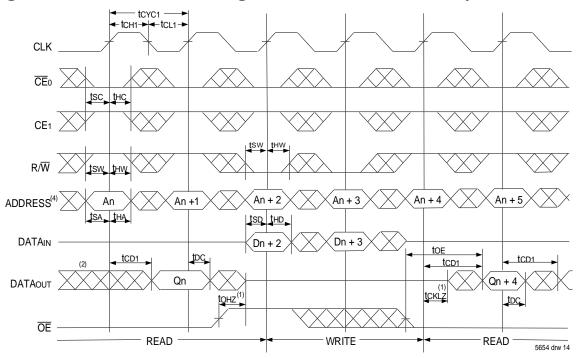


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3.  $\overline{\text{CE}}_0$  and  $\overline{\text{ADS}} = \text{VIL}$ ; CE1,  $\overline{\text{CNTEN}}$ , and  $\overline{\text{CNTRST}} = \text{VIH}$ . "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since  $\overline{ADS} = V_{IL}$  constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

## Timing Waveform of Flow-Through Read-to-Write-to-Read ( $\overline{OE} = V_{IL}$ )<sup>(3)</sup>

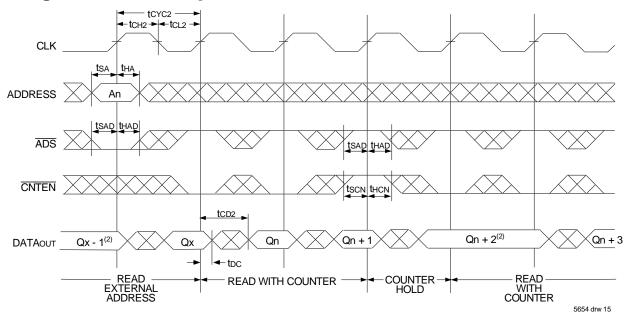


## Timing Waveform of Flow-Through Read-to-Write-to-Read (OE Controlled)(3)

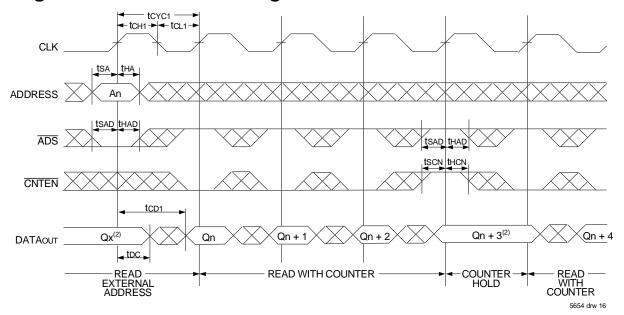


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance is determined by the previous cycle control signals.
- CEo and ADS = VIL; CE1, CNTEN, and CNTRST = VIH. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since  $\overline{ADS} = VIL$  constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

## Timing Waveform of Pipelined Read with Address Counter Advance<sup>(1)</sup>

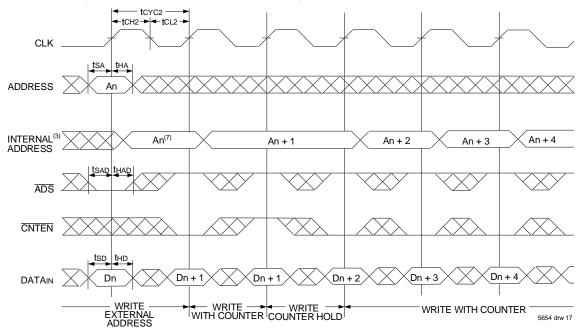


## Timing Waveform of Flow-Through Read with Address Counter Advance<sup>(1)</sup>

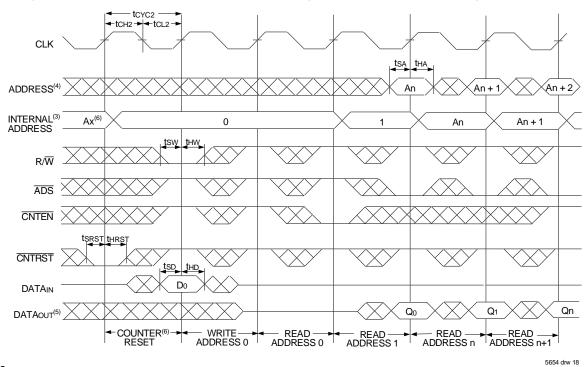


- 1.  $\overline{\text{CE}}_0$  and  $\overline{\text{OE}}$  = Vil., CE1, R/ $\overline{\text{W}}$ , and  $\overline{\text{CNTRST}}$  = Vil.
- 2. If there is no address change via  $\overline{ADS} = VIL$  (loading a new address) or  $\overline{CNTEN} = VIL$  (advancing the address), i.e.  $\overline{ADS} = VIH$  and  $\overline{CNTEN} = VIH$ , then the data output remains constant for subsequent clocks.

# Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)<sup>(1)</sup>



## Timing Waveform of Counter Reset (Pipelined Outputs)(2)



- 1.  $\overline{CE_0}$  and  $R/\overline{W} = V_{IL}$ ; CE<sub>1</sub> and  $\overline{CNTRST} = V_{IH}$ .
- 2.  $\overline{CE}_0 = VIL$ ;  $CE_1 = VIH$ .
- 3. The "Internal Address" is equal to the "External Address" when  $\overline{ADS} = VIL$  and equals the counter output when  $\overline{ADS} = VIH$ .
- 4. Addresses do not have to be accessed sequentially since  $\overline{ADS} = VIL$  constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle.
- 7. CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1' Address is written to during this cycle.

### **A Functional Description**

The IDT70T9169/59 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the address counters for fast interleaved memory applications.

 $\overline{\text{CE}}_0 = \text{VIH}$  or CE1 = VIL for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70T9169/59's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required to get valid data on the outputs.

## **Depth and Width Expansion**

The IDT70T9169/59 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT70T9169/59 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 18-bit or wider applications.

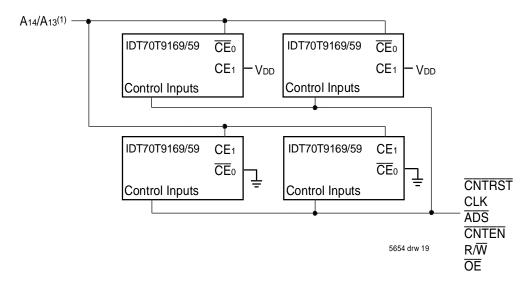
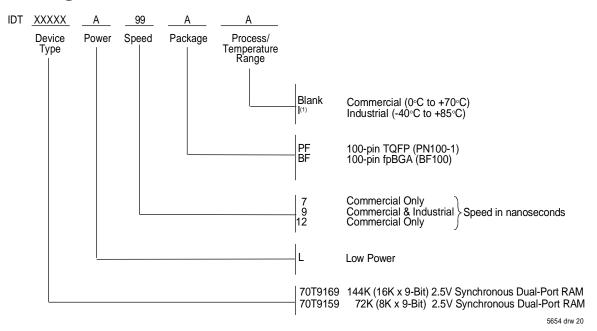


Figure 4. Depth and Width Expansion with IDT70T9169/59

### NOTE

1. A<sub>14</sub> is for IDT70T9169, A<sub>13</sub> is for IDT70T9159.

## **Ordering Information**



1. Contact your local sales office for Industrial temp range for other speeds, packages and powers.

## **Datasheet Document History**

07/08/02: Initial Public Release



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